



DOCUMENT TITLE:
**MARKETING OUTLINE DRAWING 13MM X 13MM, 144 BALLS, TECSBGA/CSBGA,
4 LAYER 1.00 MM PITCH**

DOC ID # 21-0314 NEW REV: A

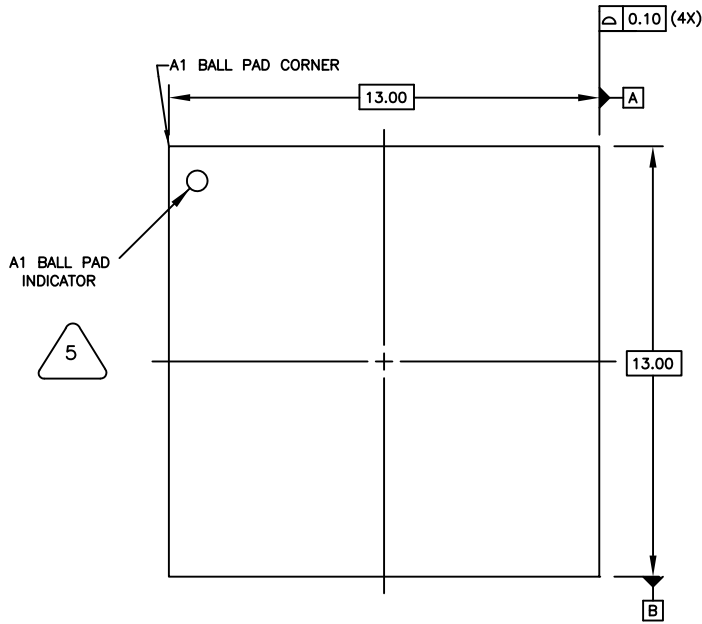
ECN#: HQ-08-5581 EFFECTIVE DATE: 07/16/08

ORIGINATOR: JEFF WALKER

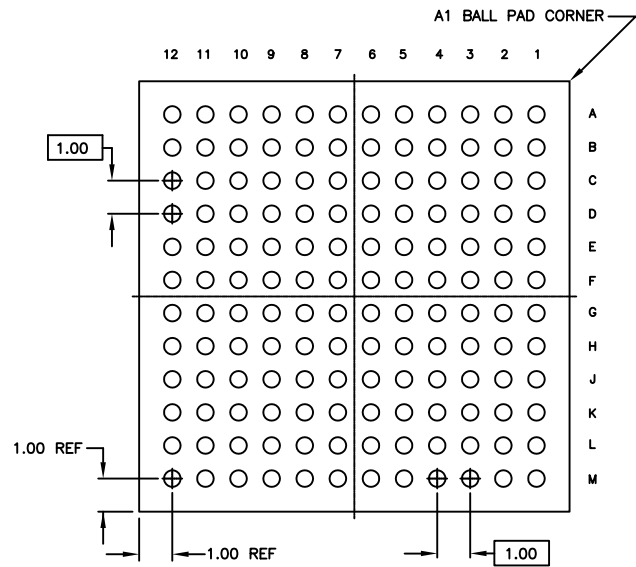
MOST RECENT CHANGES

FROM	TO
DALLAS DOCUMENT CONTROL SYSTEM DOC 56-G6016-001. LOGO-DALLAS/MAXIM	INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL LOGO-MAXIM

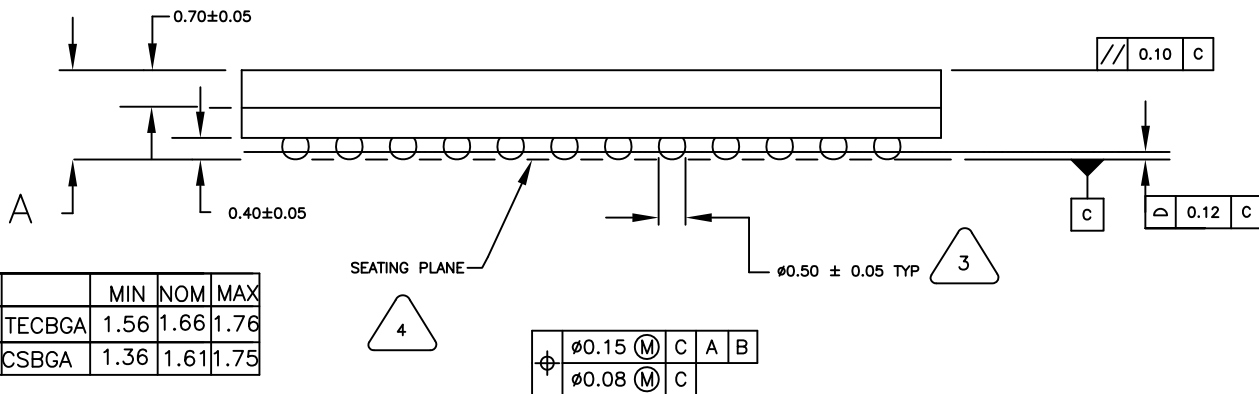
REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A			



TOP VIEW




BOTTOM VIEW
(BALL SIDE)



SIDE VIEW

NOTES:

1. DIMENSION IS MM.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. A1 BALL PAD CORNER I.D.

SIGNATURE		DATE					
DDC. CONTROL:							
ENGR. MGR:				MARKETING OUTLINE DRAWING			
MFG. ENGR:				13MM X 13MM, 144 BALLS, TECSBGA/CSBGA, 4 LAYER			
CHECKED BY:		TWM		12/02		SIZE	
DRAWN BY:		JFD		12/02		A	
				SCALE		N/A	
				PART NO.		21-0314	
				REV.		A	
				SHEET		1 of 1	

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	ECN# HQ-08-5581. INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL. LOGO-MAXIM	07/16/08	JW



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REVISION
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